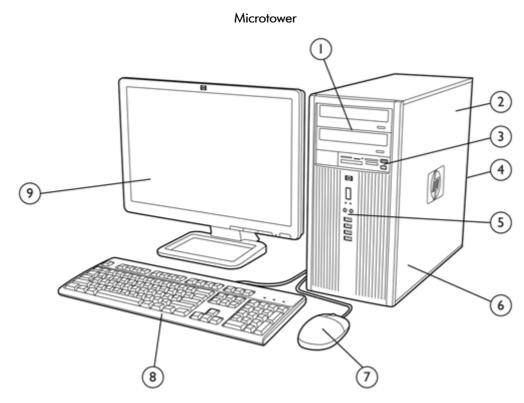
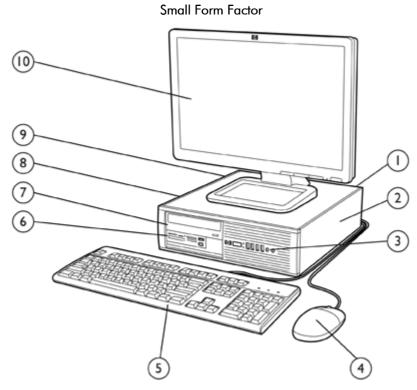
Overview



- (2) 5.25" external optical disk drive bays
 (2) 3.5" internal hard disk drive bays
- 320-watt standard efficiency power supply, Active Power Factor Correction (PFC)
 Optional: 89% efficient energy saving power supply
- 3. (1) 3.5" external bay for optional HP 22-in-1 Media Card Reader, pocket media drive, or other 3.5" device
- 4. Rear I/O: (6) USB 2.0, (1) standard serial port, (1) optional serial port, (1) optional parallel port, (2) PS/2, (1) RJ-45, (1) VGA, (1) audio in, (1) audio out, (1) Display Port
- 5. Front I/O: (4) USB 2.0, headphone and microphone, Dual Color Diagnostic LEDs
- 6. (1) full-height PCI slot, (2) full-height PCIe x1 slots, (1) full-height PCIe x16 slot
- 7. HP Optical Scroll Mouse (PS/2 or USB), or HP USB Laser Mouse
- 8. HP Standard Keyboard (PS/2 or USB) or HP USB Smartcard Keyboard
- 9. HP monitor (sold separately)

Overview



- 1. Rear I/O: (6) USB 2.0, (1) standard serial port, (1) optional serial port, (1) optional parallel port, (2) PS/2, (1) RJ-45, (1) VGA, audio in/out, (1) DisplayPort
- (1) low profile PCI slot, (2) low profile PCIe x1 slots, (1) low profile PCle x16 slot
- 3. Front I/O: (4) USB 2.0, headphone and microphone, Dual Color Diagnostic LEDs
- HP Optical Scroll Mouse (PS/2 or USB), or HP USB Laser Mouse
- HP Standard Keyboard (PS/2 or USB) or HP USB Smartcard 10. HP Monitor (sold separately) Keyboard

- (1) 3.5" external bay for optional HP 22-in-1 Media Card Reader, pocket media drive, or other 3.5" device
- (1) 5.25" external bay for optional optical drive, or other 7. 5.25" device (bay tilts up for device removal and insertion)
- (1) 3.5-inch internal drive bay supporting primary hard disk 8. drive
- 9. 240-watt power supply Optional: 89% efficient energy saving power supply

Overview

At A Glance

- The HP Compaq 6005 Pro Business PC is a high performance PC with energy efficient features designed to exceed expectations and deliver results without compromise
- AMD 785G chipset with integrated ATI Radeon HD 4200 graphics supporting DirectX 10.1
- Side Port Memory for increased power savings and increased graphics performance
- Standard dual display support (DisplayPort and VGA)
- AMD Phenom[™] II Quad-Core, Triple-Core, and Dual-Core processors; AMD Athlon[™] II Dual-Core processors; AMD Sempron[™] processor; all processors with AMD-V support
- Embedded TPM1.2 compliant security module* (Vista Bit-Locker ready)
- Support for up to 500-GB SATA 3.0Gb/s Smart IV hard drives
- Value-added software on select models
 - O HP Support Assistant
 - O HP Software Agent
 - O McAfee Anti-Virus with 60 day Live Update Subscription
 - O HP Vision Diagnostics software
 - O Microsoft Office 2007
 - O PDF Complete
 - O Computrace Enabler for Desktops (select countries)
 - O HP System Software manager
 - O HP Power Manager
 - O Firefox- HP Virtual Browser
- Value-added software available for free download from the Web (http://www.hp.com/go/easydeploy)
 - O HP Client Automation Starter Edition
 - O HP SoftPaq Download Manager
 - O HP System Software Manager
 - O HP Client Catalog for Microsoft SMS
- Fully compatible software OS image across all models (Microtower, Small Form Factor)
- HP BIOS for security, manageability and software image stability
- Protected by HP Services, including standard warranties up to 5-5-5 (terms and conditions vary by country; certain restrictions and exclusions apply)
- Selected configurations with global availability easily set up and ordered through HP.com Business to Business portals (http://h10019.www1.hp.com/business-site/index.html)
- Tailored HP Factory Express deployment and lifecycle services available (http://h71028.www7.hp.com/enterprise/cache/97688-0-0-225-121.aspx)

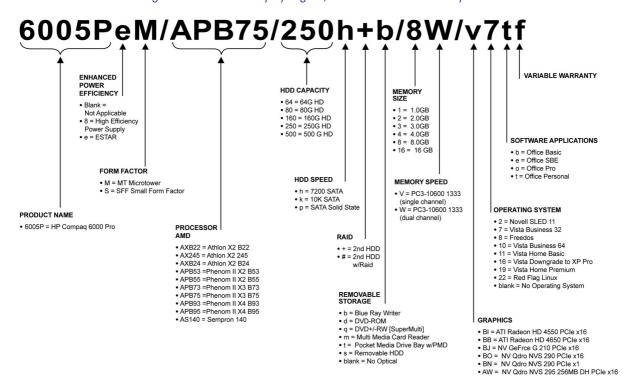


^{*}TPM module disabled where use is restricted by law; for example, Russia.

Configurable Components - Select Models (localized by Regions)

Model Key and Example

NOTE: This diagram is an example that illustrates how to read the model number. It is not intended to give every available configuration choice specified in the body of this document and may include references to features that are out of date and no longer available. Because the configurations offered vary by region, some features listed may not be available in all countries.





Standard Features and Configurable Components (availability may vary by country)

Operating System - One of the following

Preinstalled Genuine Windows 7 Professional Edition 32*
Genuine Windows 7 Professional Edition 64*

Windows XP Professional (available through downgrade rights

from Genuine Windows 7 Professional)*+
Genuine Windows 7 Home Premium Edition 32*
Genuine Windows 7 Home Premium Edition 64*
Genuine Windows 7 Home Basic Edition 32*
Genuine Windows Vista Business 32**
Genuine Windows Vista Home Basic 32**

Windows XP Professional (available through downgrade rights

from Genuine Windows Vista Business)**++

Novell SUSE Linux Enterprise Desktop 11†

FreeDOS

Supported Genuine Windows Vista Business 64**

Genuine Windows Vista Enterprise 32**
Genuine Windows Vista Enterprise 64**

Certified Novell SUSE Linux Enterprise Desktop 11†

Red Hat Enterprise Linux++

NOTE: Windows XP Mode, available as a separate download for Windows 7 Professional, works with virtualization software such as Windows Virtual PC to run older Windows XP business software on the Windows 7 desktop.

* Offered when Windows 7 is generally available. System may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality.

See http://www.microsoft.com/windows/windows-7/ for details.

- ** Certain Windows Vista product features require advanced or additional hardware. See: http://www.microsoft.com/windowsvista/getready/hardwarereqs.mspx and: http://www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor.
- + Windows 7 Professional disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custom image.
- ++ Windows Vista Business disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custom image.
- † The following features are not supported by Novell SUSE Linux Enterprise Desktop:
 - HP 22-in-1 Media Card Reader with PCI Card
 - HP ProtectTools
 - SATA Blu-ray Writer playback of commercial movies
 - Broadcom NetXtreme Gigabit Ethernet PCle NIC Plus Card
 - 2nd serial port adapter (including low profile)
 - Power Management features (US ENERGY STAR)



Standard Features and Configurable Components (availability may vary by country)

†† The following features are not supported by Red Hat Enterprise Linux:

- HP 22-in-1 Media Card Reader with PCI Card
- Integrated 1.2 TPM Embedded Security Chip
- Broadcom NetXtreme Gigabit Ethernet PCle NIC Plus Card
- LSI PCEe x1 Hi-Speed 56K International SoftModem
- HP FireWire / IEEE 1394 PCI Card (full height and low profile)
- 2nd serial port adapter (including low profile)
- HP Wireless 802.11b/g/n PCle x1 Card
- HP USB Smartcard Keyboard
- Power Management features (US ENERGY STAR)

Value-added Software (on	HP Software Agent
select models; not	HP Support Assistar
included with FreeDOS)	ווט כי כי ני

HP Support Assistant

HP Systems Software Manager

HP Vision Diagnostics HP Power Manager

McAfee Total Protection Anti-Virus with 60 day trial

Subscription

Roxio Creater Business (select models) Firefox-HP Virtual Browser

SRS Premium Sound Software for HP Thin USB

Powered Speakers (select models)

Microsoft Office 2007 Basic Microsoft Office 2007 Personal

Microsoft Office 2007 Professional

Microsoft Office 2007 Small Business Edition

Integrated DASH 1.1 Manageability Computrace Enabler for Desktops (select

countries)*

HP Skyroom (trial version) Corel WinDVD (select models)

* Requires HP LoJack Pro for ProtectTools for full functionality. Tracking and tracing subscription sold separately.

Value-added Software			
(available for free			
download from the Web			
http://www.hp.com/go/			
easydeploy)			

HP Client Automation – Starter Edition

HP Client Catalog for Microsoft SMS

HP Client Manager from Symantec

HP Systems Software Manager

HP SoftPag Download Manager

HP Disk Sanitizer, External Edition

Features

Value-added Services and HP Stable Platform Program **Business-to-Business Portals**

HP Global Series Services

Factory Express Deployment and Lifecycle Services

TPM 1.2 Security chip*

* TPM module disabled where use is restricted by law; for example, Russia.

Standard Features and Configurable Components (availability may vary by country)

Service and Support

On-site Warranty and Service Note 1: This limited warranty and service offering delivers parts, labor and on-site repair for terms up to 5 years. Response time is next business-day Note 2 and includes free telephone support Note 3 24 x 7. Global coverage Note 2 ensures that any product purchased in one country and transferred to another non-restricted country will remain fully covered under the original warranty and service offering. Some countries/regions do not offer one year onsite and labor. For HP Care Pack services see: http://www.hp.com/go/lookuptool.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

	Microtower	Small Form Factor
Chassis Dimensions $(H \times W \times D)$	14.85 x 6.95 x 16.96 in 377.2 x 176.5 x 430.8 mm	3.95 x 13.30 x 14.90 in 100.3 x 337.8 x 378.5
Optional Tower Stand Dimensions (H x W x D)	N/A	1.05 x 6.95 x 7.83 in (26.75 x 176.46 x 198.87 mm)
System weight*	20.5 lb (9.3 kg)	16.0 lb (7.26 kg)
System volume	1739 cu in	941.63 cu in
Shipping weight*	28.79 lb (13.06 kg)	26.70 lb (12.11 kg)
Maximum supported weight (desktop orientation)	N/A	77.1 lb (35 kg)
Shipping box dimensions $(H \times W \times D)$	19.69 x 12.2 x 23.62 in 500 x 310 x 600 mm	9.72 x 19.68 x 22.67 in 246.9 x 499.9 x 575.8 mm

^{*} Configured with 1 hard drive, 1 optical drive, no diskette drive, and no PCI card.

Power Supply 320W power supply – active PFC 240W power supply – active PFC **Energy Efficient Power** 320W 89% efficient power supply – active PFC

240W 89% efficient power supply – active PFC

Supply

Ports

USB 2.0 10 (4 front, 6 rear) 1 standard with 2nd optional Serial **Parallel** 1 optional PS/2 1 keyboard, 1 mouse Video analog for integrated graphics

available via HP DisplayPort to DVI-D Adapter

Support for Multi-Monitor 1 Standard DisplayPort and 1 Standard VGA

Integrated High Definition audio with internal speaker

Front – mic and headphone

Rear – input (supports microphone or line input), line out Integrated Broadcom NetXtreme Gigabit Ethernet BCM 5761

NIC (RJ-45)

DVI output

Audio



Standard Features and Configurable Components (availability may vary by country)

Chipset	AMD 785G chipset	MT X	SFF X
Processor	AMD Sempron Processors with HyperTransport™ Technology:		
One of the following		V	Χ
Characteristics	AMD Sempron 140 Processor (2.7 GHz, 1 MB L2 cache, HT bus 3.0)	Χ	۸
	AMD Athlon II Dual-Core Processors with HyperTransport Technology:	.,	.,
	AMD Athlon II X2 215 Processor (2.7 GHz, 2MB L2 cache, HT bus 3.0)	Χ	Χ
	AMD Athlon II X2 B22 Processor (2.8 GHz, 2 MB L2 cache, HT bus 3.0)	Χ	Χ
AMD Athlon II X2 B24 Processor (3.0 GHz, 2 MB L2 cache, HT bus 3.0	AMD Athlon II X2 B24 Processor (3.0 GHz, 2 MB L2 cache, HT bus 3.0)	Χ	Χ
	AMD Phenom II Dual-Core Processors with HyperTransport Technology:		
	AMD Phenom II X2 B53 Processor (2.8 GHz, 1 MB L2 cache, 7 MB Total cache, HT bus 3.0)	Χ	Χ
	AMD Phenom II X2 B55 Processor 3.0 GHz, 1 MB L2 cache, 7 MB Total cache, HT bus 3.0)	Χ	Χ
	AMD Phenom II Triple-Core Processors with HyperTransport Technology:		
	AMD Phenom II X3 B73 Processor 2.8 GHz, 1.5 MB L2 cache, 7.5 MB Total cache, HT bus 3.0)	Χ	Χ
	AMD Phenom II X3 B75 Processor 3.0 GHz, 1.5 MB L2 cache, 7.5 MB Total cache, HT bus 3.0)	Χ	Χ
	AMD Phenom II Quad-Core Processors with HyperTransport Technology:		
	AMD Phenom II X4 B93 Processor 2.8 GHz, 2 MB L2 cache, 8 MB Total cache, HT bus 3.0)	Χ	Χ
	AMD Phenom II X4 B95 Processor 3.0 GHz, 2 MB L2 cache, 8 MB Total cache, HT bus 3.0)	Χ	Χ

Memory

Supports un-buffered non-ECC DDR3 SDRAM

AMD processors support un-buffered non-ECC DDR3 SDRAM (synchronous dynamic random access memory) at a frequency of up to 1333 MHz.

NOTE: The actual memory speed for DDR3 SDRAM depends on the processor and memory configuration. The maximum speed of 1333 MHz requires an AMD Phenom II processor that supports it. In addition, AMD Phenom II processors with CPUID 100F42h require that no more than one DIMM slot per channel be populated with a DDR3 memory module in order to support a memory speed of 1333 MHz.

System memory upgrades are accomplished by adding DDR3 SDRAM module(s) to empty DIMM slots on the system board.

CAUTION: Voltage is supplied to the memory modules whenever the computer is connected to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board. The computer must be shut down with the AC power removed (disconnect AC power cord at rear chassis or at AC outlet) prior to adding or removing SDRAM modules.



Standard Features and Configurable Components (availability may vary by country)

HP recommends dual-channel configurations for the best memory performance.

For best performance, add memory to each memory channel and do not inter-mix memory module speeds. If memory module speeds are inter-mixed, the memory operating frequency will default to the slowest speed.

Microtower and Small Form Factor

Maximum Memory*

Supports up to 16GB of un-buffered non-ECC DDR3 SDRAM.

The DIMM connectors for Channel A slot 3 and Channel B slot 4 are black and these slots must always be populated first in the channel. Not all possible memory configurations are represented in the table below.

NOTE: For systems configured with more than 3GB of memory and a 32-bit operating system, all memory may not be available to the OS due to system resource requirements. Addressing memory above 4GB requires a 64-bit operating system.

Total Memory	DIMM Slot Population				
	Channel A Channel B				
	1 (white)	3 (black)	2 (white)	4 (black)	
1-GB				1GB	
(Single Channel)					
2-GB		1GB		1GB	
(Dual Channel)					
3-GB		2GB		1GB	
(Dual Channel)					
4-GB		2GB		2GB	
(Dual Channel)					
4-GB	1GB	1GB	1GB	1GB	
(Dual Channel)					
8-GB	2GB	2GB	2GB	2GB	
(Dual Channel)					
16-GB maximum	4GB	4GB	4GB	4GB	
(Dual Channel)					

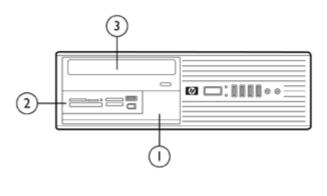
Standard Features and Configurable Components (availability may vary by country)

Expandability	Microtower	Small Form Factor
PCI slots	1 full-height	1 low-profile
Max power per slot	35W	35W
PCle x1 slot	2	2
Max power per slot	10W	10W
PCle x16 slot	1 full-height	1 low-profile
Max power per slot	75W	35W
External Bays		
3.5"	1	1
5.25"	2	1
IDE		
Internal 3.5" HDD Bays	2	1
Hard Drive Controller (SATA) Supported	SATA	SATA
Hard Drive Interfaces Supported	SATA 3.0Gb/s	SATA 3.0Gb/s

Microtower

1 2 3 3 4 (Internal) 5 (Internal)

Small Form Factor



Standard Features and Configurable Components (availability may vary by country)

Storage - Drive Support								
		Microtower			Small Form Factor			
	Media Card Reader or Pocket Media Drive (optional)	5.25" Serial ATA Devices	3.5" Serial ATA Devices	Media Card Reader or Pocket Media Drive (optional)	5.25" Serial ATA Devices	3.5" Serial ATA Devices		
Quantity Supported	1	2	2	1	1	2		
Position Supported	3	1,2	3,4,5	2	1	2,3		
Controller	USB/Diskette	SATA	SATA	USB/Diskette	SATA	SATA		

NOTE: The SATA port labeled SATA3 on the system board can be enabled by the BIOS as an eSATA port. Using it for an eSATA drive will require a separately purchased cable with an eSATA connector.

		MT	SFF
Hard Drive	160-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
One or two of the	250-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
following	320-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	500-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	80-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 10,000 RPM, NCQ, Smart III)	Χ	Χ
	160-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 10,000 RPM, NCQ, Smart III)	Χ	Χ
	3.5" Removable 160-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	3.5" Removable 250-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	3.5" Removable 500-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	2 nd hard drive, 160-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	2 nd hard drive, 250-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	2 nd hard drive, 320-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	2 nd hard drive, 500-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 7200 RPM, NCQ, Smart IV)	Χ	Χ
	2 nd hard drive, 80-GB SATA 3.0-Gb/s Hard Drive (16MB Cache,10,000 RPM, NCQ, Smart III)	Χ	Χ
	2 nd hard drive,160-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 10,000 RPM, NCQ, Smart III)	Χ	Χ
	RAID 0,1 support	Χ	Χ
	NOTE: NCQ functionality requires a user set-up BIOS setting.		

Standard Features and Configurable Components (availability may vary by country)

Solid State Drive	64-GB Solid State Drive	Χ	Χ
	RapidDrive	Χ	Χ

NOTE: RapidDrive is an optional new productivity solution available only on the HP Compaq 6005 Pro. It links the Solid State Drive (SSD) and Hard Drive together to form one virtual drive that combines the advantages of both technologies. Pre-installed applications reside on the SSD for reduced access time, yet the usual limitations of SSD storage are eliminated by linking it with a large hard drive.

Removable Storage – One or more of the following depending on	Pocket Media Drive 250GB Pocket Media Drive Media Reader	Χ	X
form factor (see Storage – Drive Support section	HP 22-in-1 Media Card Reader (USB connection on the system board)	Χ	Χ
above)	HP 22-in1 (with 1394) Media Card Reader (USB connection on the system board)	Χ	Χ
	Optical Drives		
	SATA DVD-ROM Drive	Χ	Χ
	SATA SuperMulti LightScribe DVD Writer Drive	Χ	Χ
	SATA Blu-ray Writer	Χ	X
Security	TPM 1.2 Embedded Security Chip*	Х	X
,	HP Desktop Security lock kit (lock and cable)	Χ	Χ
	HP Chassis Security Kit	Χ	Χ
	Security cable with Kensington lock	Χ	Χ
	HP Solenoid Hood Lock and Sensor	Χ	Χ
	Optional HP ProtectTools 5.0 security software suite	Χ	Χ
	Optional LoJack Pro tracking and tracing subscription	Χ	Χ
	Optional USB Port Disable at factory (user configurable via BIOS)	Χ	Χ
	RAID 0,1 support	Χ	Χ
	* TPM module disabled where use is restricted by law; for example, Russia.		
NIC	Broadcom NetXtreme Gigabit Ethernet BCM 5761 (integrated on system board)	Х	X
	Broadcom NetXtreme Gigabit Ethernet Plus PCle NIC	Χ	Χ
Wireless	HP 802.11 b/g/n Wireless PCIe x1 card (full height bracket)	Х	
	HP 802.11 b/g/n Wireless PCle x1 card (low profile bracket)		Χ
Modem	LSI PCIe x1 56K International SoftModem	Х	X



Standard Feature	es and Configurable Components (availability may vary by country)		
Graphics	Integrated ATI Radeon HD 4200 Graphics*	Χ	Χ
·	ATI Radeon HD 4650 (1 GB DH) PCle x16 Graphics Card	Χ	
	ATI Radeon HD 4550 Dual Head PCIe x16 Graphics Card	Χ	Χ
	NVIDIA Quadro NVS 290 PCle x1 Graphics Card	Χ	Χ
	NVIDIA Quadro NVS 290 (256MB DH) PCle x16 Graphics Card	Χ	Χ
	NVIDIA Quadro NVS 295 (256MB DH) PCle x16 Graphics Card	Χ	Χ
	NVIDIA GeForce 310 DP PCIe x16 Graphics Card	Χ	Χ
	HP DisplayPort to VGA Adapter	Χ	Χ
	HP DisplayPort to DVI-D Adapter	Χ	Χ
	* Side Port memory: The AMD 785G chipset provides a Side Port memory interface for 128 MB of dedicated frame buffer DDR3 memory with a device width of x16 for th graphics chip.	ne integrat	ed
Audio	Integrated High Definition audio with Realtek ALC261 codec (all ports are stereo)	Χ	Х
	Microphone and Headphone front ports	Χ	Χ
	Line-out and Line-In rear ports*	Χ	Χ
	Multistreaming capable*	Χ	Χ
	Internal Speaker	Χ	Χ
	HP Thin USB Powered Speakers (optional)	Χ	Χ
	* Re-taskable ports; see technical specifications page 21.		
Input Devices	Keyboard - One of the following		
	HP PS/2 Standard Keyboard	Χ	Χ
	HP USB Standard Keyboard	Χ	Χ
	HP Smartcard Keyboard	Χ	Χ
	HP USB PS/2 Washable Keyboard	Χ	Χ
	HP USB Mini Keyboard	Χ	Χ
	Mouse - One of the following		
	USB 2-Button Laser Mouse	Χ	Χ
	PS/2 2-Button Optical Scroll Mouse	Χ	Χ
	USB 2-Button Optical Scroll Mouse	Χ	X
Miscellaneous	2 nd serial port adapter	Х	
	2 nd serial port adapter (low profile)		Χ
	Parallel port adapter	Χ	Χ
	HP FireWire / IEEE 1394 Adapter	Χ	Χ
	Tower stand		Χ



After-Market Options (availability may vary by region)

		MT	SFF	Part Number
Communications	Wireless LAN			
	HP 802.11 b/g/n Wireless PCle x1 card	Χ	Χ	FH971AA
	NICs	V	V	E
	Broadcom NetXtreme Gigabit Ethernet Plus PCIe NIC	Χ	Χ	EA833AA
	Modem LSI PCIe x1 56K International SoftModem	Χ	Χ	FH970AA
	LSI PCIE XT SOK International Sottiviodem		^	
Graphics	Multi head solutions			
	ATI Radeon HD 4550 (256MB DH) PCle x16 Card	Χ	Χ	AT042AA
	ATI Radeon HD 4650 (1 GB DH) PCle x16 Graphics Card	Χ		VN566AA
	HP DisplayPort to VGA Adapter	Χ	Χ	AS615AA
	HP DisplayPort to DVI-D Adapter	Χ	Χ	FH973AA
	NVIDIA Quadro NVS 290 (256MB DH) PCle x1 Graphics Card	Χ	Χ	KN586AA
	NVIDIA Quadro NVS 290 (256MB DH) PCle x16 Graphics Card	Χ	Χ	KG748AA
	NVIDIA GeForce 310 DP PCIe x16 Graphics Card	Χ	Χ	VG885AA
Hard Drives	Serial ATA Hard Drives			
	HP 160-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Χ	Χ	PY277AA
	HP 250-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Χ	Χ	PY278AA
	HP 320-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Χ	Χ	FH963AA
	HP 500-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Χ	Χ	KW347AA
	HP 80-GB SATA 3.0-Gb/s 10,000 rpm Hard Drive	Χ	Χ	EM172AA
	HP 160-GB SATA 3.0-Gb/s 10,000 rpm Hard Drive	Χ	Χ	EW222AA
	HP Removable SATA Hard Drive Enclosure (Frame & Carrier)	Χ	Χ	RY102AA
	HP Removable SATA Hard Drive Enclosure (Carrier Only)	Χ	Χ	RY103AA
Input/Output Devices	HP PS/2 Standard Keyboard	Х	Х	DT527A
прод Сограг Болгоо	HP USB Standard Keyboard	Χ	X	DT528A
	HP USB Smartcard Keyboard	Χ	X	ED707AA
	HP USB Gray Standard Keyboard	Χ	X	DT529A
	HP USB PS/2 Washable Keyboard	Χ	X	VF097AA
	HP USB Mini Keyboard	Χ	Χ	AS601AA
	HP 2.4 GHz Wireless Keyboard and Mouse	Χ	X	NB896AA
	HP USB Laser Mouse	Χ	X	GW405AA
	HP PS/2 2-Button Optical Scroll Mouse	Χ	X	EY703AA
	HP USB 2-Button Optical Scroll Mouse	Χ	Χ	DC172B



After-Market Optic	ons (availability may vary by region)			
Memory (DIMMs)	PC3-10600 (DDR3, 1333MHz) DIMMs Non-ECC			
, , ,	HP 4-GB PC3-10600 (DDR3 1333 MHz) DIMM	Χ	Χ	VH638AA
	HP 2-GB PC3-10600 (DDR3 1333MHz) DIMM	Χ	Χ	AT024AA
	HP 1-GB PC3-10600 (DDR3 1333 MHz) DIMM	Х	Χ	AT023AA
Monitors	All HP monitors are supported that accept a graphics output provided by this PC. The LP3065 monitor can be supported by installing a graphics card that supports a dual-link DVI-D output.			
Multimedia	HP Thin USB Powered Speakers	Х	Χ	KU901AV
Optical Drives	DVD-ROM Drive			
•	HP SATA DVD-ROM Drive	Χ	Χ	AH047AA
	DVD Writer			
	SATA Blu-ray Writer	Χ	Χ	AR481AA
	HP SATA SuperMulti LightScribe DVD Writer Drive	Х	Χ	GF343AA
Removable Storage	Removable Drives			
	HP 250GB Pocket Media Drive	Χ	Χ	FE477AA
	Multimedia			
	HP 22-in-1 Media Card Reader	Χ	Χ	FX273AA
	HP 22-in-1 (with 1394) Media Card Reader	Χ	Χ	KN518AA
Security	Kensington lock	Χ	Χ	PC766A
	HP Business PC Security Lock	Χ	Χ	PV606AA
	HP Chassis Security Kit	Χ	Χ	AR639AA
	HP ProtectTools 5.0 Client Security Software including HP ProtectTools Security Manager Credential Manager for HP ProtectTools Device Access Manager for HP ProtectTools Drive Encryption for HP ProtectTools Embedded Security for HP ProtectTools Java Card Security for HP ProtectTools LoJackPro for HP ProtectTools Privacy Manager for HP ProtectTools File Sanitizer for HP ProtectTools	X	X	TBD
	HP 2009 Wall Mount/Security Sleeve		Χ	TBD
	THE ZOOF WAIL MOUTH, Security Steeve		^	טסו



After-Market Opti	ons (availability may vary by region)			
Manageability	HP Client Configuration Manager, Premium Edition	Х	X	T3488AA (use T3489AA for 1000 licenses)
Brackets/Stands	HP 2009 Small Form Factor Tower Stand		Х	VN569AA
Miscellaneous	HP Serial Port Adapter Kit	Χ	Χ	PA716A
Accessories	HP Parallel Port Adapter Kit	X	Χ	KD061AA
	HP FireWire / IEEE 1394 Adapter	Χ	Χ	PA997A



Technical Specifications

Unit Environment and Operating Conditions	Microtower	Small Form Factor

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

	117
Temperature Range	Operating: 50° to 95° F (10° to 35° C)* Non-operating: -22° to 140° F(-30° to 60° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 10,000 ft (3048 m) Non-operating: 30,000 ft (9144 m)

^{*} Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

	Microtower		Small Form Factor	
Power Supply	320-watt BTX power supply - Active PFC	320-watt 89% efficient* BTX power supply - Active PFC	240-watt BTX power supply - Active PFC	240-watt 89% efficient* BTX power supply - Active PFC
Operating Voltage Range	100-240VAC	100-240VAC	100-240VAC	100-240VAC
Rated Voltage Range	115V/230V	115V/230V	115V/230V	115V/230V
Rated Line Frequency	50/60 Hz	50/60 Hz	50/60 Hz	50/60 Hz
Operating Line Frequency Range	47-63 Hz	47-63 Hz	47-63 Hz	47-63 Hz
Rated Input Current	5.5A	5.5A	4A	4A
Heat Dissipation (NEED TO UPDATE)	Typical 315 btu/hr (79 kg-cal/hr) Maximum 1575 btu/hr (397 kg-cal/hr)	Typical 270 btu/hr (68 kg-cal/hr) Maximum 1280 btu/hr (322 kg-cal/hr)	Typical 315 btu/hr (79 kg-cal/hr) Maximum 1260 btu/hr (317 kg-cal/hr)	Typical 270 btu/hr (68 kg-cal/hr) Maximum 1025 btu/hr (258 kg-cal/hr)
Power Supply Fan	Variable speed fan	Variable speed fan	Variable speed fan	Variable speed fan
ENERGY STAR Compliant		Х		Х
FEMP Standby Power Compliant (<1W in S5 - Power Off)**	Х	Х	Х	Х
Power Consumption in ENERGY STAR Mode - Suspend to RAM (S3) (Instantly Available PC)	<2.4W	<2.4W	<2.4W	<2.4W



Technical Specifications

- * Energy efficient power supply is a requirement for ENERGY STAR qualification in conjunction with a select range of processors and modules
- ** Power consumption in the Off/Apparent Off mode is measured and reported with the network interface controller "Wake on LAN" feature disabled in F10 Setup (default is "enabled").

ROM BIOS Information

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Business desktop computer into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 12 languages.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Security HP BIOS offers a robust and flexible set of security features to help the system administrator secure their systems from removal of sensitive data, and help prevent access by unauthorized users. Ability to disable USB ports.
- Tracking and tracing capabilities in case of theft available in select countries (subscription sold separately).
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies to assist in operating the HP Business Desktop computer in any enterprise environment.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates from within DOS (Flashlite), BIOS updates from within Windows (HPQFlash, SSM), HP Client Manager, and fail-safe recovery. In addition, the HP Business Desktop BIOS Utilities tool enables replicated BIOS setup throughout the Enterprise; it is available from within the BIOS software and from the support website.

Additional HP BIOS Features

- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system
 configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be made
 to BIOS settings using F10 setup or under the OS.
- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration
 management, allowing operating systems and applications to manage power based on activity and usage. Provides power
 conservation features under Windows XP.
- Mute internal speaker
- Disable USB ports

Other Features	Description	
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).	
	 Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. 	
SMBIOS Ver. 2.6	System Management BIOS, previously known as DMI BIOS, for system management	
	information	
Dual-State Power Button	Power button acts as both an on/off button and suspend-to-sleep button	



Technical Specifications

Serviceability Features of System			
Dual Color Power LED on Front of Comp	outer (Indicates Normal Operations and Fault (Conditions)	
Diagnostic LED Explanation Table	Number of 1-second red LED blinks followed by 2-second pause, then repeats: 2-processor thermal protection activated 3-processor not installed 4-power supply failure 5-memory error 6-video error 7-PCA failure (ROM detected failure prior to video) 8-invalid ROM, bootblock recover mode		
System/Emergency ROM	• Flash ROM	CMOS Battery Holder for easy Replacement	
Flash Recovery with Video	5 Aux Power LED on System PCA	 Processor ZIF Socket for easy Upgrade 	
 Over-Temp Warning on Screen (Requires IM Agents) 	Clear Password Jumper	DIMM Connectors for easy Upgrade	
Restore CD	Clear CMOS Switch	NIC LEDs (integrated) (Green & Amber)	

Serviceability Features of Chassis		-
 Dual Color Power and HD LED - To Indicate Normal Operations and Fault Conditions 	Color coordinated cables and connectors	 Tool-less Hood Removal (thumbscrews for Microtower, spring- loaded latch for Small Form Factor)
Front power switch	System memory can be upgraded on Microtower without removing any internal components	 Tool-less Hard Drive, CD & Diskette Removal
Additional Features	Description	
Towerable	Small Form Factor can be oriented as a towe	er (in addition to desktop orientation)
Drive Self Tests (DPS) DPS Access through F10 Setup during Boot	sector of the hard drive for physical fa Running independently of the operatin Windows-based diagnostics utility or the produces an evaluation on whether the and needs to be replaced. The system expands on the Self-Monit	ns critical physical components and every ults and then reports any faults to the user. It is system, it can be accessed through a hrough the computer's setup procedure. It is hard drive is the source of the problem oring, Analysis, and Reporting Technology ms diagnostic that alerts the user to certain
SMART IV Technology* (Self-Monitoring, Analysis and Reporting Technology)	types of failures. Allows hard drives to monitor their own healt were predicted • Predicts failures before they occur. Tra parameters such as re-allocated secto count • By avoiding actual hard drive failures,	th and to raise flags if imminent failures acks fault prediction and failure indication r count, spin retry count, calibration retry
DASH 1.1 support (Desktop and Mobile Architecture for System Hardware)	A standards initiative for representing out-of- systems. It is a secure, web-services based su	band management capability for computer



Technical Specifications

ASF 2.0 support (Alert Standard Format) Industry-standard specification for network alerting in operating system-absent environments



Technical Specifications - Audio

High Definition Audio Type Integrated

High Definition Stereo

Codec

Yes – 4-channel Realtek ALC261 codec

Audio Jacks Front microphone-In (150-K ohm Input Impedance)

Rear Line-In/Microphone input (150-K ohm Input Impedance, function is

configurable by audio driver)

Rear Line-Out* (190 ohms Output Impedance, expects at least a 10-K ohm

load)

Front Headphone-Out (0.5 Ohm Output Impedance, expects at least a 32

ohm load)

NOTES:

Internal Speaker Amplifier is for Internal Speaker only. External Speakers need to be powered externally.

The rear input port can function as a Line-In or Microphone-In jack.

The front Microphone jack is retaskable to support headphones. When functioning as a headphone jack the same audio stream will be sent to both front jacks.

The front Microphone jack is also retaskable to function as a Line-in jack.

The Realtek Control Panel software required to reassign audio ports is preloaded but must be installed by the customer before these functions can be performed.

Multistreaming Capable Multistreaming can be enabled in the Realtek control panel to allow

independent audio streams to be sent to/from the front and rear jacks.

Sampling 8 kHz - 192 kHz

Wavetable Syntheses

(software)

Yes – Uses OS soft wavetable

Analog Audio Yes

Number of Channels on

Stereo (Left & Right channels)

Line-Out (mono/stereo)

Internal Audio Speaker

1.5 W

Power Rating

Internal Speaker

Ower Ruling

Yes; ability to mute internal speaker through F10 Setup

External Speaker Jack

(Line-Out)

Yes



Technical Specifications - Communications

Integrated Broadcom NetXtreme Gigabit Ethernet BCM 5761 Connector RJ-45

Controller Broadcom 5761 PCI-Express LAN Controller

Memory 8 MB NVRAM serial Flash
Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB, 802.3u, and 802.3x

Bus architecture PCI-E

Data path width
Single channel, PCI-E

Bus-master DMA

1.8W @ 3.3V

Boot ROM support Yes

Network transfer mode Full-duplex

Half-duplex (not available for the 1000BASE-T transceiver)

Network transfer rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps

1000BASE-T (full-duplex) 2000 Mbps (actual rate limited by PCI Bus)

Environmental Operating temperature 32° to 131°F (0° to 55° C)

Operating humidity 131° F (55° C) with 5% to 95% non-condensing

humidity

Management capabilities ACPI, WOL and DMI 2.0, PXE 2.0, WfM 2.0, Broadcom mgmt utility,

ASF2.0, DASH 1.0 and DASH 1.1 profiles

Broadcom NetXtreme Gigabit Ethernet Plus PCIe NIC Card Connector RJ-45

Controller Broadcom 5761 PCI-Express LAN Controller

Memory 8 MB NVRAM serial Flash
Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB, 802.3u, and 802.3x

Bus architecture PCI-E

Data path widthSingle channel, PCI-EData transfer modeBus-master DMA

Hardware certifications FCC class B, Canada and US NRTL Mark, C-Tick for Australia, BSMI for

Taiwan, VCCI for Japan, MIC for Korea, GOST for Russia, UL listed

(E212044), European Union Notice (CE 0682)

Power requirement 1.8W @ 3.3V

Boot ROM support Yes

Network transfer mode Full-duplex

Half-duplex (not available for the 1000BASE-T transceiver)



Technical Specifications - Communications

Network transfer rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps

1000BASE-T (full-duplex) 2000 Mbps (actual rate limited by PCI Bus)

Environmental Operating temperature 32° to 131°F (0° to 55° C)

Operating humidity 131° F (55° C) with 5% to 95% non-condensing

humidity

Dimensions 2.75 in x 4.13 in (7 cm x 10.5 cm), low profile compatible

Management capabilities ACPI, WOL and DMI 2.0, PXE 2.0, WfM 2.0, Broadcom mgmt utility,

ASF2.0, DASH 1.0 and DASH 1.1 profiles

HP 802.11b/g/n Wireless Dimensions (L x H)
PCle x1 Card Weight

Dimensions (L x H) 3.3 x 4.7 inches (8.5 x 12 cm)

Weight 0.08 pounds (40 g)
Controller Ralink RT2790

System interface PCIExpress x1

Network standard 802.11 b/g/n

Frequency band 2.400 - 2.497 GHz

Operating temperature 14° to 149°F, operating (-10° to 65°C, operating)

Storage temperature

-40° to 176°F, non-operating (-40° to 80°C, non-operating)

Humidity 10-90% operating

5-95% non-operating

Operating voltage 3.3V +/- 9%

12V +/- 8%

Power consumption Platform/WLAN Mode Power Consumption

Maximum Power 10 Watts

Consumption

Transmit Only 4 Watts maximum averaged power over 1

second

Transmit Packet or Active 1000 mA peak current for 100 microseconds or

Scanning longer

3

Receive Only Mode or Idle 3 Watts maximum averaged over 1 second

without IEEE PSP mode

enabled

Idle, with IEEE PSP mode

1.0 Watts maximum averaged over 1 second

enabled

Transmit Disabled (turned 50 mW maximum, averaged over 1 second

off in software)

Platform in S3 or S4 5 mW maximum, averaged over 1 second

(power removed from Low Profile PCI Express Card)



Technical Specifications - Communications

Output power	802.11b modes	802.11g modes	EWC modes
(approximately)	+19 dBm +/- 1.0 dB maximum	+17 dBm +/- 1.0 dB maximum	+17 dBm +/- 1.0 dB maximum (total power in all transmit chains)
Receive sensitivity	Mode	Data rate	Sensitivity
	802.11b	1 Mbps	-94 dBm
	802.11b	11 Mbps	-85 dBm
	802.11g	6 Mbps	-91 dBm
	802.11g	18 Mbps	-85 dBm
	802.11g	48 Mbps	-75 dBm
	802.11g	54 Mbps	-72 dBm
	EWC (2.4 GHz)	6.5 Mbps	-87 dBm
	EWC (2.4 GHz)	54 Mbps	-82 dBm
	EWC (2.4 GHz)	81 Mbps	-78 dBm
	EWC (2.4 GHz)	162 Mbps	-74 dBm
	EWC (2.4 GHz)	270 Mbps	-68 dBm
	EWC (2.4 GHz)	300 Mbps	-64 dBm
Data transfer rate	Data Rate (MCS)	Minimum Throughput	
	1 Mbps (802.11 b)	700 kbps	
	2 Mbps (802.11 b)	1.4 Mbps	
	5.5 Mbps (802.11 b)	3.5 Mbps	
	11 Mbps (802.11 b)	5.9 Mbps	
	12 Mbps (802.11 g)	6 Mbps	
	18 Mbps (802.11 g)	9 Mbps	
	24 Mbps (802.11 g)	12 Mbps	
	36 Mbps (802.11 g)	18 Mbps	
	48 Mbps (802.11 g)	21 Mbps	
	54 Mbps (802.11 g)	22.5 Mbps	
	6.5 Mbps (20 MHz EWC)	4.5 Mbps	
	13 Mbps (20 MHz EWC)	9 Mbps	
	19.5 Mbps (20 MHz EWC)	13.5 Mbps	
	26 Mbps (20 MHz EWC)	18 Mbps	
	39 Mbps (20 MHz EWC)	27 Mbps	
	52 Mbps (20 MHz EWC)	36 Mbps	
	58.5 Mbps (20 MHz EWC)	40 Mbps	
	65 Mbps (20 MHz EWC)	45 Mbps	
	78 Mbps (20 MHz EWC)	54 Mbps	
	104 Mbps (20 MHz EWC)	72 Mbps	
	117 Mbps (20 MHz EWC)	81 Mbps	



Technical Specifications - Communications

Security

country

130 Mbps (20 MHz EWC) 91 Mbps 13.5 Mbps (40 MHz 8 Mbps

EWC)

27 Mbps (40 MHz EWC) 16 Mbps 40.5 Mbps (40 MHz 24 Mbps

EWC)

54 Mbps (40 MHz EWC) 32 Mbps 81 Mbps (40 MHz EWC) 48 Mbps 108 Mbps (40 MHz EWC) 64 Mbps 121.5 Mbps (40 MHz 72 Mbps EWC)

25 14 (40 14) 514(6)

135 Mbps (40 MHz EWC) 81 Mbps

• IEEE and WiFi compliant 64 / 128 bit WEP encryption

AES: CCM

802.1x authentication

• WPA: 802.1x. WPA-PSK and TKIP

WPA2 certificationIEEE 802.11i

• Cisco Certified Extensions, all versions through V5

Antenna HP part number 497792-001

Certifications Wi-Fi certified

Certifications for use by United States, Canada, Peru, Taiwan

LSI PCle x1 56K International SoftModem Data Transmission Technology speeds: 56,000 Kbps maximum downstream data, controllerless

NOTE: 56 Kbps technology refers to download speeds only and requires compatible modems at server sites. Other conditions may limit modem speed. FCC limitations allow a maximum of 53 Kbps during download

transmissions.

Data Speeds (Upload only) 33,600/31,200/28,800/26,400/21,600/19,200/

16,800/14,400/12,000/9,600/7,200/4,800/2,400/1,200/300

Data Standards ITU-T V.90, ITU-T, ITU-T V.34, V.44, V.42, V.42bis21, V.32bis, Bell 212A,

and Bell 103

Fax Speeds 14,400/12,000/9,600/7,200/4,800/2,400/1,200/300 b/s

Fax Mode Capabilities ITU-T T.31 class 1 FAX, V. 17, V.29, V.27ter, and V.21 Channel 2

Error Correction and V.44, 42bis, V.42 and MNP2-5 Data Compression

Power Management PCI Bus Power Management Interface Specification (PCI-PM) Revision 1.2,

Appendix A. D0, D3hot, and D3cold. Wake on Ring state when in D3cold. If the power management event (PME) feature is enabled in D3cold, a modem can wake the system via WAKE# (WAKEN) or beacon. Meets PCI Express

1.1 standard.

Upgradeability Driver upgradeable for future enhancements

Video ITU-T V.80 video ready interface



Technical Specifications - Communications

Other TIA/EIA 602 standard AT command set

Integrated DTE interface with speeds of up to 115.2 Kbps, parallel 16550a

UART-compatible interface

Optional ring wakeup signal

Operating Temperature 32° to 158° F (0° to 70° C)
Operating Humidity 20% to 90%, non-condensing

Power Requires a 3.3-V auxiliary power rail on PCI express bus

Uses only one PCI express load (i.e., one grant/request pair), one shared

IRQ, one electrical load

Chipset LSI SV92EX - Integrated PCI interface with 3.3-V tolerant buffers and

CardBus support

Dimensions (L X H) Complies with PCI express low profile specifications-6.7 x 2.3 in (17.0 x 5.8

cm) and supports high- and low-profile brackets

Connection Single RJ-11 connector

Other Features Digital line protection, call progress monitoring via on-board piezo device,

support for high profile and low profile brackets, PnP ID support

Safety UL recognized to UL 1950, 3rd edition (U.S. and Canada); IEC 950 (TUV,

NEMKO, DEMKO, SEMKO); CE Mark, EC 950 (TUV, NEMKO, DEMKO,

SEMKO, CE mark

EMC FCC Part 15, IC ES003, EN 55022, 3rd edition, EN 55024, annex A, EN

61000-4-6, EN 61000-4-8

Telecom FCC Part 68, IC-CS-03 (Canada); Worldwide PTT approvals

Not available in Korea or the Republic of South Africa.

Other The SV92EX device is packaged in a 32-pin micro leadless chip carrier

(MLCC). The SV92EX is fully compliant with the PCI Express revision 1.1

specification. WHQL approved; ASPM compliant.



Technical Specifications - Graphics

Integrated ATI HD 4200 Gaphics	Memory Controller Clock Speed Maximum Color Depth Multi-display Support Graphics/Video API Support Output connectors VGA DAC Frequency	Variable and User selectable in BIOS set 500MHz 32 bpp Yes DX10, OpenGL 2.0 1 VGA, 1 DisplayPort (Multi-Mode (DP+ 400 MHz	
Resolutions	Resolution	Maximum Refre	sh Rate (Hz)
Supported		Analog Connection	Digital Connection
	640x480	85	60
	800x600	85	60
	1024x768	85	60
	1280x720	85	60
	1280x1024	85	60
	1440x900	75	60
	1600x1200	85	60
	1680x1050	75	60
	1920x1080	85	60
	1920x1200	85	60
	1920x1440	85	60
	2048x1536	75	60
	2560x1600		60
	Resolution 640x480 800x600 1024x768 1280x720 1280x1024 1440x900 1600x1200 1680x1050 1920x1080 1920x1200 1920x1440 2048x1536	Maximum Refree Analog Connection 85 85 85 85 85 75 85 75 85 85	ssh Rate (Hz) Digital Connection 60 60 60 60 60 60 60 60 60 60 60 60 60

ATI Radeon HD 4650 (1 GB DH) PCle x16 Graphics Card (FH Only) Bus type PCI Express (x16 lanes)

Maximum vertical refresh rate 85 Hz

Display support Integrated 400 MHz RAMDAC

Display max resolution 2560 x 1600 digital, 2048 x 1536 analog

Board display options Supports two displays through any combination of two of the three output

ports.

Board configurationSpecificationDescriptionGraphics ChipRV730ProCore clock600 MHzMemory clock500 MHz

Frame buffer 1 GB DDR3, 128 bit wide

Maximum power 55 W

Languages supported 24 languages: English, Arabic, Chinese Simplified, Chinese Traditional,

Czechoslovakian, Danish, Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian, Polish,

Portuguese, Russian, Spanish, Swedish, Thai, Turkish

Compliance standards EMC Emissions:



Technical Specifications - Graphics

a) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment

EMC Immunity:

CISPR 24:1997/EN 55024:1998 - Information Technology Equipment - Immunity Characteristics - Limits and Methods of Measurement.

ATI Radeon HD 4650 (1 GB) PCle x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	·	· ,	
	Maximum Refresh Rate (Hz)		
Resolution	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R*	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	60**	

^{*} Max HDMI resolution is 1080p

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

ATI Radeon HD 4550 (256 MB DH) PCle x16 Graphics Card Bus type PCI Express (x16 lanes)

Maximum vertical refresh rate 85 Hz

Display support Integrated 400 MHz RAMDAC

Display max resolution 1900 x 1200 digital, 2048 x 1536 analog

Board display options Supports two displays via included DMS-59 to dual VGA cable or 2 DVI

monitors via optional DMS-59 to dual DVI cable kit part number:

DL139A. 4-pin mini-DIN S-video connector for TV output

Board configuration Specification Description
Graphics Chip RV710
Core clock 600MHz
Memory clock 800 MHz

Frame buffer 256 MB DDR2, 64 bit wide

Languages supported 24 languages: English, Arabic, Chinese Simplified, Chinese Traditional,

Czechoslovakian, Danish, Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian, Polish,

Portuguese, Russian, Spanish, Swedish, Thai, Turkish



^{**} Only supported when using a dual-link DVI connection

Technical Specifications - Graphics

Compliance standards

EMC Emissions:

a) FCC Part 15, Subpart B - Unintentional Radiators, Class B Computing Devices for Home & Office Use

b) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment

- c) Canadian Standard ICES-003 is equivalent to CISPR22
- d) Taiwanese Standard BSMI
- e) Japanese VCCI
- f) Australian C-Tick
- g) Korean (KCC)

EMC Immunity:

CISPR 24:1997/EN 55024:1998 - Information Technology Equipment - Immunity Characteristics - Limits and Methods of Measurement.

ATI Radeon HD 4550 DH PCle x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Refresh Rate (Hz)		
Resolution	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	N/A	

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

NVIDIA Quadro NVS 290 Bus type PCle x1

PCle x1 Graphics Card

Low profile, both ATX and low profile brackets included

Graphics Controller Integrated Quadro 290 2D graphics processor unit (GPU)

Memory 256 MB DDR2

Connector

Single high-density DMS-59 Flex Connector

Low-profile, 2.586 x 6.6 in (6.57 x 16.76 cm)

Multi-monitor support

Dual analog or digital (Single Link DVI) monitors
(DVI support requires optional DVI cable kit DL139A)

RAMDAC Dual 350 MHz (integrated)

Maximum pixel clock 350 MHz

Overlay planes One 1-bit Video overlay plane



Technical Specifications - Graphics

High-definition Video Full screen, full frame video playback of HDTV and DVD content

Processor (HDVP) DVD-ready motion compensation for MPEG-2

Independent hardware color controls for video overlay Hardware color-space conversion (YUV 4:2:2 and 4:2:0)

IDCT motion compensation

5-tap horizontal by 3-tap vertical filtering

8:1 up/down scaling

Input/Output connectors DMS-59

Board display options Supports two displays via included DMS-59 to dual VGA cable or 2 DVI

monitors via optional DMS-59 to dual DVI-I single-link connectors cable

kit part number: DL139A.

Board configuration Specification Description

Description G86-825
Core clock 460 MHz
Memory clock 400 MHz

Frame buffer 256 MB DDR2, 64 bit wide

NVIDIA Quadro NVS 290 PCle x1 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Refresh Rate (Hz)		
Resolution	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	N/A	

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

Technical Specifications - Graphics

NVIDIA Quadro NVS 290 Form Factor 256MB Dual Head PCle x16 Graphics Card

Low Profile **Bus Type** PCle x16

Memory 256 MB 400MHz DDR2 SDRAM unified frame buffer, Z-buffer and Texture

storage

DMS-59, includes DMS-59 to Dual DVI-I cable. DMS-59 to Dual VGA cable Connector

available as an option.

Display Resolution

Support

Dual integrated analog display controllers supporting up to two analog displays at 2048x1536 @ 85Hz on both displays or dual digital displays at

1920x1200 (single-link).

nVIEW advanced multi-display desktop and application management

seamlessly integrated into Microsoft Windows

RAMDAC Integrated dual 400MHz

Color planes 32-bit color buffer Overlay planes Hardware supported

nView architecture Advanced multi-display desktop & application management seamlessly

integrated into Microsoft Windows.

Multi-Monitor support

DVI support

Dual monitor support DMS-59 (to dual DVI-SL)

High-definition Video Processor (HDVP)

Full-screen, full-frame video playback of HDTV and DVD content

DVD-ready motion compensation for MPEG-

2Independent hardware color controls for video overlay Hardware color-space conversion (YUV 4:2:2 and 4:2:0)

IDCT motion compensation

5-tap horizontal by 3-tap vertical filtering

8:1 up/down scaling

Supported graphics APIs OGL 2.1 & DX10 Support; Shader Model 4.0

NVIDIA GeForce 310 DP PCle x16 **Graphics Card**

Bus type PCI Express (x16 lanes)

Maximum vertical

refresh rate

85 Hz

Display support Integrated 400 MHz RAMDAC

Display max resolution 2560x1600 digital, 2048 x 1536 analog

NVIDIA GeForce 310 DP PCle x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.



Technical Specifications - Graphics

Resolution	Maximum Refresh Rate (Hz)		
	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	60*	

Only supported when using a dual-link DVI or DP connection.

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

Board display options	Supports two	o displays via	the DisplayPort and	DVI connectors
-----------------------	--------------	----------------	---------------------	----------------

Board contiguration	Specification	Description
	Graphics Chip	RV620

Core clock 750 MHz Memory clock 500 MHz

Frame buffer 512 MB DDR3, 64 bit wide

HDMI only)

Audio Support (through Integrated HD Audio codec supports linear PCM and Dolby® Digital (7.1) audio formats for HDMI output

Operating systems support

Windows 7 Home Basic*, Windows 7 Home Premium*, Windows 7 Professional Edition 32*, Windows 7 Professional Edition 64*, Windows 7 Ultimate Edition 32*, Windows 7 Ultimate Edition 64*, Windows Vista Business 32†, Windows Vista Business 64†, Windows Vista Home Basic 32†, Windows Vista Home Basic 64†, Windows XP Professional or Windows XP Home 32†.

*This system may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See: http://www.microsoft.com/windows/windows-7/ for details.

Windows 7 Business disk may be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order at least 25 customer systems with the same custom image

† Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit:

http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit: http://www.windowsvista.com/systemrequirements.



Technical Specifications - Graphics

Linux x86 and x86 64 distributions using XFree86 or X.Org‡.

‡Linux drivers are available from ATI's website and may be available in a Linux distribution. Refer to the Open Source and Linux from HP website:

http://www.hp.com/wwsolutions/linux/products/clients/ for support information.

Core power

22 W (max)

Dimensions (H x D)

2.71 in x 6.60 in (68.90 mm x 167.65 mm)

Weight

0.30 lb (134.3 g)

Option kit contents

- NVIDIA GeForce 310 DP PCle x16 Graphics Cardwith full height bracket attached
- DVI to VGA adapter
- Software CD with graphics drivers
- Low profile bracket to convert the card for using in a low profile chassis
- Warranty documentation

Compliance standards

EMC Emissions:

a) FCC Part 15, Subpart B - Unintentional Radiators, Class B Computing Devices for Home & Office Use

- b) CISPR22: 1997/EN 55022:1998 Class B Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment
- c) Canadian Standard ICES-003 is equivalent to CISPR22
- d) Taiwanese Standard BSMI
- e) Japanese VCCI
- f) Australian C-Tick
- g) Korean (MIC)

EMC Immunity:

CISPR 24:1997/EN 55024:1998 - Information Technology Equipment - Immunity Characteristics - Limits and Methods of Measurement.

HP DisplayPort to DVI-D Connectors Adapter

DisplayPort and DVI-D single link connector

Adapter length Adapter weight 7.5 in (19.0 cm) .10 lbs (.05 kg)

Technical Specifications - Graphics

HP DisplayPort to VGA

Adapter

Connectors DisplayPort and VGA connector

Adapter length 8 in (20 cm)
Adapter weight .1 lbs (.06 kg)

Maximum vertical refresh rate 85 Hz

Display support 162 MHz RAMDAC

Display max resolution 1600x1200

HP DisplayPort to VGA adapter display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as they may not have been tested and qualified by HP. Using the HP DisplayPort to VGA Adapter may require an update to the graphics driver installed on your system. To install the most up-to-date graphics driver go to: www.hp.com.

Resolution	Max refresh rate
640x480	85
800x600	85
1024x768	85
1280x720	85
1280x1024	85
1440x900	75
1600x1200	60
1680x1050	60
1920x1080	60-R
1920x1200	60-R
NOTE: 60-R denotes reduced blanking timings are used. Not all r	nonitors support reduced blanking timing.



Technical Specifications - Internal Storage

7200	RPM Serial ATA	
Hard I	Drives	

500-GB

500,107,862,016 bytes Capacity

Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.89 cm)

Up to 3 Gb/s

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer

Rate (Maximum)

16 MB

Buffer Single Track Seek Time (typical reads,

2.0 ms includes controller Average 11 ms overhead, including Full-Stroke 21 ms settling)

7,200 rpm Rotational Speed Logical Blocks 976,773,168

41° to 131° F (5° to 55° C) Operating Temperature

320-GB 320,072,933,376 bytes Capacity

> 1 in (2.54 cm) Height

Width Media diameter: 3.5 in (8.89 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer

Rate (Maximum)

Up to 3 Gb/s

Buffer 8 MB

Seek Time (typical reads, Single Track 1.0 ms includes controller Average 8.5 ms overhead, including Full-Stroke 18 ms settling)

7,200 rpm Rotational Speed 625,142,448 Logical Blocks

Operating Temperature 41° to 131° F (5° to 55° C)

250-GB 250,059,350,016 bytes Capacity

> 1 in (2.54 cm) Height

Width Media diameter: 3.5 in (8.89 cm)

Up to 3 Gb/s

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer

Rate (Maximum)

Buffer 8 MB



Technical Specifications - Internal Storage

Seek Time (typical reads, Single Track 1.0 ms includes controller 8.5 ms Average overhead, including Full-Stroke 18 ms settling)

Rotational Speed 7,200 rpm 488,397,168 Logical Blocks

41° to 131° F (5° to 55° C) Operating Temperature

160-GB Capacity 160,041,885,696 bytes

> Height 1 in (2.54 cm)

Width Media diameter: 3.5 in (8.89 cm)

Physical size: 4 in (10.2 cm)

Interface Serial ATA (3.0 Gb/s)

Synchronous Transfer

Rate (Maximum)

8 MB

Up to 3 Gb/s

Buffer

0.9 ms Seek Time (typical reads, Single Track includes controller Average 9.3 ms overhead, including Full-Stroke 18 ms settling)

7,200 rpm Rotational Speed Logical Blocks 312,581,808

41° to 131° F (5° to 55° C) Operating Temperature

10,000 RPM Serial ATA 160-GB

Hard Drives

160,041,885,696 bytes Capacity

Height 1 in (2.54 cm)

Width Media diameter: 2.5 in (? cm)

Physical size: 4 in (10.2 cm)

Serial ATA (1.5 Gb/s), Native Command Queuing enabled Interface

Synchronous Transfer

Rate (Maximum)

Cache 16 Mbytes

Seek Time (typical reads, Single Track 0.3 ms includes controller Average 4.6 ms overhead, including Full-Stroke 10.2 ms settling)

Up to 3.0 Gb/s

Rotational Speed 10,000 rpm

Logical Blocks 312,581,808

Operating Temperature 41° to 131° F (5° to 55° C)

80-GB Capacity 80,026,361,856 bytes

> Height 1 in (2.54 cm)

Width Media diameter: 2.5 in (? cm)

Physical size: 4 in (10.2 cm)



Technical Specifications - Internal Storage

Interface Serial ATA (1.5 Gb/s), Native Command Queuing enabled

Synchronous Transfer Up to 3.0 Gb/s

Rate (Maximum)

Cache 16 Mbytes

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.3 msAverage
Full-Stroke4.6 ms10.2 ms

Rotational Speed 10,000 rpm Logical Blocks 156,301,488

Operating Temperature 41° to 131° F (5° to 55° C)

64 GB Solid State Drive Capacity 64 GB

NAND Flash Memory Multi Level Cell (MLC) with wear leveling controller

Interface type SATA 3Gb/sec

Dimensions-external $2.74 \times 0.37 \times 4 \text{ in } (6.98 \times 0.95 \times 10.2 \text{ cm})$

 $(W \times H \times D)$

Weight 0.14 lb (65 g)

Internal transfer rate Write speed Up to 220 MB/s
Read speed Up to 120 MB/s

Host transfer rate Ultra DMA mode Up to 150 MB/s

Power DC power requirement 5 VDC 5%-100 mV ripple p-p

Total power consumption <1.12Watt

Environmental Temperature (operating) 32° to 158° F (0° to 70° C)

(all conditions, non- Relative Humidity 5% to 95%

condensing) (operating)

Maximum Wet Bulb 84° F (29° C)

Temperature (operating)

Regulations UL, CSA, EN 60950-2000, CISPR Pub 22 Class B, CNS 13438, AS/NZS

CISPR 22:2002 Class B, R1113 and C1172 Class B



^{*} For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.

Technical Specifications - Input/Output Devices

USB Standard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)	
		Dimensions $(L \times W \times H)$	18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)	
		Weight	2 lb (0.9 kg) minimum	
	Electrical	Operating voltage	$+$ 5VDC \pm 5%	
		Power consumption	50-mA maximum (with three LEDs ON)	
		System interface	USB Type A plug connector	
		ESD	CE level 4, 15-kV air discharge	
		EMI - RFI	Conforms to FCC rules for a Class B computing device	
		Microsoft® PC 99 - 2001	Functionally compliant	
	Mechanical	Languages	38 available	
		Keycaps	Low-profile design	
		Switch actuation	55-g nominal peak force with tactile feedback	
		Switch life	20 million keystrokes (using Hasco modified tester)	
		Switch type	Contamination-resistant switch membrane	
		Key-leveling mechanisms	For all double-wide and greater-length keys	
		Cable length	6 ft (1.8 m)	
		Microsoft PC 99 - 2001	Mechanically compliant	
		Acoustics	43-dBA maximum sound pressure level	
	Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
		Non-operating	-22° to 140° F (-30° to 60° C)	
		temperature		
		Operating humidity	10% to 90% (non-condensing at ambient)	
		Non-operating humidity	20% to 80% (non-condensing at ambient)	
		Operating shock	40 g, six surfaces	
		Non-operating shock	80 g, six surfaces	
		Operating vibration	2-g peak acceleration	
		Non-operating vibration	4-g peak acceleration	
		Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
		Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence	
	Approvals	UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC		
	Ergonomic compliance			
	Kit contents	Keyboard, installation guide, warranty card, safety and comfort		



Technical Specifications - Input/Output Devices

PS/2 Standard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Dimensions (L \times W \times H)	18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	+ 5VDC ± 5%
		Power consumption	50-mA maximum (with three LEDs ON)
		System interface	PS/2 6-pin mini din connector
		ESD	CE level 4, 15-kV air discharge
		EMI - RFI	Conforms to FCC rules for a Class B computing device
		Microsoft PC 99 - 2001	Functionally compliant
	Mechanical	Languages	38 available
		Keycaps	Low-profile design
		Switch actuation	55-g nominal peak force with tactile feedback
		Switch life	20 million keystrokes (using Hasco modified tester)
		Switch type	Contamination-resistant switch membrane
		Key-leveling mechanisms	For all double-wide and greater-length keys
		Cable length	6 ft (1.8 m)
		Microsoft PC 99 - 2001	Mechanically compliant
		Acoustics	43-dBA maximum sound pressure level
	Environmental	Operating temperature	50° to 122° F (10° to 50° C)
		Non-operating temperature	-22° to 140° F (-30° to 60° C)
		Operating humidity	10% to 90% (non-condensing at ambient)
		Non-operating humidity	20% to 80% (non-condensing at ambient)
		Operating shock	40 g, six surfaces
		Non-operating shock	80 g, six surfaces
		Operating vibration	2-g peak acceleration
		Non-operating vibration	4-g peak acceleration
		Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
		Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence
	Approvals	UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC ANSI HFS 100, ISO 9241-4, and TUVGS	
	Ergonomic compliance		
HP USB Smartcard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Form factor	USB basic Smart Card keyboard
		Colors	Carbonite/Silver



Operating voltage

Dimensions $(H \times W \times D)$

Weight

Electrical

18.2 x 6.3 x 1.3 in (46.3 x 16.1 x 3.3 cm)

2 lb (0.9 kg) minimum

+ 5VDC \pm 5%

Technical Specifications - Input/Output Devices

Power consumption 100-mA maximum (with four LEDs ON)

System interface USB Type A plug connector ESD CE level 4, 15-kV air discharge

EMI - RFI Conforms to FCC rules for a Class B computing

device

Microsoft PC 99 - 2001 Functionally compliant

Mechanical Languages 30+ available

Keycaps Low-profile design

Switch actuation 55 g nominal peak force with tactile feedback Switch life 20 million keystrokes (using Hasco modified

tester)

Switch type Contamination-resistant membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Environmental Operating temperature 50° to 122° F (10° to 50° C)

Non-operating -22° to 140° F (-30° to 60° C)

temperature

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock40 g, six surfacesNon-operating shock80 g, six surfacesOperating vibration2-g peak accelerationNon-operating vibration4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 42 in (107 cm) on concrete, 16-drop sequence

SMARTCARD function Support All ISO 7816 smart cards

Interface Reads from and writes to all ISO7816-1, 2, 3, 4

memory and microprocessor smart cards (T=0,

T=1

Chipset SCM STCII

Standard APIs supported PC/SC, EMV2000, SET

Power USB Port

Short circuit detection (protects smart card and

reader)

Power supply compliant with ISO7816 and EMV

(5V, 60 mA)

Supports 3-V and 5-V cards

Power consumption 250-mA maximum draw (50 mA for the

keyboard with three LEDs ON and 200-mA maximum startup current using a high-current,

60-mA smart card)



Technical Specifications - Input/Output Devices

Communication	From card	Programmable from
---------------	-----------	-------------------

9,600 baud to 115,200 baud

From computer Up to 38,400 baud

Landing mechanism Contact device Friction contact

Up to 100,000 Card insertions rating

insertion cycles

89/336/CEE guideline

Interface modes USB communications through USB port

SCM protocol

Automatic card insertion/removal detection

Reader performance

Electro-magnetic

interface

USB connection

standards **USA** USAFCC part 15

Europe

HP USB 2-Button Laser Mouse

Scroll Wheel 24

Electrical

Maximum Rotation Speed 48 rats/sec Switch Type wheel

Switch Life Button - 3,000,000

Wheel - 1,000,000 times Tilt switch - 500,000 times

Environmental **Operating Temperature** 32° to 104° F (0° to 40° C)

Non-operating

Temperature

-4° to 140° F (-20° to 60° C)

Operating Humidity 10% to 90% (non-condensing at ambient) Non-operating Humidity 20% to 80% (non-condensing at ambient)

Operating Shock 40 g, six surfaces 80 g, six surfaces Non-operating Shock **Operating Vibration** 2-g peak acceleration 4-g peak acceleration Non-operating Vibration

+ 5VDC \pm 5% Operating Voltage

Power Consumption

MTBF > 150,000 hrs

ESD IEC-61000-4-2 criteria B, Contact discharge:

+/- 4kV, Air discharge: +/- 8kV

FCC Class B EMI-RFI PC98 PC 99 Compliant

Mechanical Resolution 800dpi

> Tracking Speed 25 cm/sec Acceleration 0.5mm Switch Actuation 0.6N (60gf)



Technical Specifications - Input/Output Devices

Switch Life Button - 3,000,000

> Wheel - 1,000,000 times Tilt switch - 500,000 times

Cable Length 1850mm

PC98-99 PC99 compliant

UL60950-1, UL 94, UL 746 (A-E), UL 796 Regulatory Approvals

TUV/GS: EN 60950-1, EN 60825-1

FCC Class B, UL 1950, cUL, TUV GS, CE, C-tick, VCCI, BSMI, RRL

HP PS/2 Optical Scroll

Mouse

Dimensions (H x L x W)

3.95 x 6.21 x 11.7 cm (1.56 x 2.44 x 4.61 in)

4.44 oz (126 g)

Weight **Environmental**

-32° to 104°F (0° to 40° C) Operating temperature Non-operating -4° to 140°F (-20° to 60° C)

temperature

10% to 90% (non condensing at ambient) Operating humidity

Non-operating humidity 10% to 90% non condensing

Operating shock 40 g, 6 surfaces Non-operating shock 80 g, 6 surfaces Operating vibration 2 g peak acceleration Non-operating vibration 4 g peak acceleration

80 cm height onto asphalt tile over concrete or **Drop** (out of box)

equivalent, 5-drop in 5 direction except the cable

face

Electrical Operating voltage 5 VDC ± 10%

> Power consumption 100mA

System consumption PS/2 mini-din connector

ESD CE level 4, 15 kV air discharge

EMI-RFI Conforms to FCC rules for a Class B computing

device

Microsoft PC99 - 2001 Functionally compliant

Mechanical Resolution $400 \pm 20\% DPI$

> Tracking speed 10 in/s (25.4 cm/s) maximum Acceleration 100 in/s/s (2.54 m/s/s) Switch actuation 61 g nominal peak force

Switch life 3,000,000 operations (using Hasco modified

tester)

Low force micro-switches Switch type

Tracking mechanism life 155 mi (250 km) at average speed of 10 in/s

Cable length 6 ft (1.8 m)

Microsoft PC99 - 2001 Mechanically compliant

Width Scroll wheel 8 mm

> Diameter 1.01 in (25.6 mm)

Maximum rotation speed 48 rats/sec

Technical Specifications - Input/Output Devices

Light force micro-switch Switch type Switch life 1 million operations

Mechanical life Minimum 200,000 revolutions

Regulatory approvals Compliant UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI,

BSMI, C-Tick, MIC

HP USB Optical Scroll

Dimensions $(H \times L \times W)$ Mouse

1.5 x 4.5 x 2.5 in (3.8 x 11.6 x 6.3 cm)

Weight 0.27 lb (0.12 kg) Cable length 72.8 in (185 cm)



Double-layer

QuickSpecs

Technical Specifications - Optical Storage

HP SATA Blu-ray Writer	Height 5.25-inch, half-height, tra	
	Orientation	Either horizontal or vertical
		CATA /ATADI

Interface type SATA/ATAPI

Disc capacity 50 GB DL or 25 GB standard

Dimensions (W x H x D) 5.9 x 1.7 x 7.5 in (15.0 x 4.4 x 19.0 cm)

Weight (max) 2.0 lb (907g)

		Single-layer	Double-layer
Write speed	BD-R	2x, 4x CLV, 6x CAV	2x, 4x CLV
	BD-RE	2.3x	2x CLV
	DVD-R	2x, 4x CLV, 8x ZCLV, 8x 12x PCAV, 16x CAV	, 2x, 4x CLV
	DVD-RW	1x, 2x, 4x, 6x CLV	Not supported
	DVD+R	2.4x, 4x CLV, 8x ZCLV, 8x, 12x PCAV, 16x CAV	2.4x, 4x CLV
	DVD+RW	2.4x, 4x, 6x CLV, 8x ZCLV	Not supported
	DVD-RAM	2x, 3x CLV, 3-5x PCAV	
	CD-R	8x,16x CLV, 24x, 32x PCAV, 40x CAV	
	CD-RW	4x, 10x, 16x CLV, 24x ZCLV	
		Single-layer	Double-layer
Read speeds	BD-ROM	6x CAV	4.8x CAV
	BD-R	6x CAV	4.8x CAV
	BD-RE (SL/DL)	4.8x CAV	4.8x CAV
	DVD-ROM	16x CAV	8x CAV
	DVD-R	12x CAV	8x CAV
	DVD-RW	10x CAV	Not support
	DVD+R	12x CAV	8x CAV
	DVD+RW	10x CAV	Not support
	BDMV (AACS Compliant Disc)	4.8x CAV	
	DVD-RAM	2x, 3x CLV, 3x-5x PCAV	
	DVD-Video (CSS Compliant Disc)	8x CAV	
	CD-R/RW/ROM	40x / 40x / 40x CAV	
	CD-DA (DAE)	32x CAV	
	80 mm CD	16x CAV	
Sustained Transfer rate	BD-ROM	215.79 Mbits/s (6x) max	ζ.
	DVD-ROM	16.62 Mbytes/s (16x) max.	
	CD-ROM	6,000 KB/s (40x) max.	
Burst Transfer rate		1.5Gbps bits/s (10b side) 1.2Gbps bits/s (8b side)	

Single-layer



Technical Specifications - Optical Storage

Multimedia MPC-3 Yes

compliant

Access times Random DVD: < 140 ms (typical), CD: < 125 ms (typical)

(typical reads, including

setting)

Full Stroke DVD: < 250 ms (seek), CD: < 210 ms (seek)

Power Source SATA DC power receptacle

DC Power Requirement 5 VDC \pm 5%-100 mV ripple p-p 12 VDC \pm 5%-200 mV ripple p-p

DC Current 5 VDC -1000 mA typical, 1600 mA maximum

12 VDC -600 mA typical, 1400 mA maximum

Environmental Temperature (operating) 41° to 122° F (5° to 50° C)

(all conditions non-condensing)

Relative Humidity

10% to 90%

ndensing) (operating)

Maximum Wet Bulb 86° F (30° C)

Temperature (operating)

HP SATA SuperMulti LightScribe DVD Writer Drive

Height 5.25-inch, half-height, tray-load

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc capacity 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)

Weight (max) 2.6 lb (1.2 kg)

Write speeds DVD-RAM Up to 12X

DVD+R Up to 16X DVD+RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-R Up to 16X DVD-RW Up to 6X CD-R Up to 48X CD-RW Up to 32X

Read speeds DVD-RAM Up to 12X
DVD+RW, DVD-RW, Up to 8X

DVD+R DL, DVD-R DL

DVD-ROM DL Up to 8X DVD-ROM, DVD+R, Up to 16X

DVD-R

(typical reads, including

CD-ROM, CD-R Up to 48X CD-RW Up to 32X

(typical)

settling) Full Stroke DVD: < 250 ms (seek), CD: < 210 ms (seek)

Power SATA DC power receptacle



Technical Specifications - Optical Storage

DC Power Requirement $5 \text{ VDC} \pm 5\%-100 \text{ mV ripple p-p}$

 $12 \text{ VDC} \pm 5\%$ -200 mV ripple p-p

DC Current 5 VDC (< 1000 mA typical, 1600 mA

maximum)

 $12\ VDC\ (< 600\ mA\ typical,\ 1400\ mA$

maximum)

10% to 90%

Environmental conditions Temperature

(operating - noncondensing)

Temperature

41° to 122° F (5° to 50° C)

Relative Humidity

Maximum Wet Bulb

86° F (30° C)

SATA DVD-ROM Drive

Height 5.25-inch, half-height, tray-load

Either horizontal or vertical Orientation

Interface type SATA/ATAPI

Single layer: Up to 4.7 GB (6 times capacity of CD-ROM) Disc capacity

Double layer: Up to 8.5 GB (12 times capacity of CD-ROM)

5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm) Dimensions (W \times H \times D)

2.6 lb (1.2 kg) Weight (max)

Read speeds DVD+R/-R/+RW/ Up to 8X

-RW/+R DL /-R DL

DVD-ROM Up to 16X DVD-RAM Up to 4X CD-ROM, CD-R Up to 48X CD-RW Up to 32X

Removable Storage -Media Compatibility -DVD-ROM

Media CD-ROM CD-R CD-RW DVD-ROM DVD-ROM DL DVD-RAM DVD+R DVD+R DL DVD+RW DVD-R DVD-RW

Read Yes Yes Yes Yes Yes Yes Yes

No Yes No Yes No Yes No Yes No

Access times (typical reads, including

setting)

DVD-R DL Random

DVD: < 140 ms (typical), CD: < 125 ms

Write

No

No

No

No

No

No

No

(typical)

Full Stroke DVD: < 250 ms (seek), CD: < 210 ms (seek)

Cache Buffer 2 MB (minimum)



Technical Specifications - Optical Storage

Data Transfer Modes ATA PIO mode 4 (16.7 MB/s); ATA Multi-word

DMA mode 2 (16.7 MB/s); ATA UltraDMA Mode

3 (44.4 MB/s -default)

Power SATA DC power receptacle

DC Power Requirement 5 VDC \pm 5%-100 mV ripple p-p

 $12 \text{ VDC} \pm 5\%$ -200 mV ripple p-p

DC Current 5 VDC - <1000 mA typical, < 1600 mA

maximum

12 VDC - < 600 mA typical, < 1400 mA

maximum

Environmental Temperature 41 $^{\circ}$ to 122 $^{\circ}$ F (5 $^{\circ}$ to 50 $^{\circ}$ C)

(all conditions non-condensing)

Relative Humidity 10% to 90%

Maximum Wet Bulb 86° F (30° C)

Temperature

Technical Specifications - Removable Storage

HP 22-in-1 (with 1394) Media Card Reader USB 1.0 High-speed interface

NOTE: Requires the USB cable to be connected to the internal USB 2.0 port

or a USB 2.0 PCI card.

1394 Interface Two IEEE-1394a external ports; 1 IEEE-1394a internal port (connects to the

pass through cable on the media card reader)

Advance protocol support

• Supports hardware ECC (Error Correction Code) function

• Supports hardware CRC (Cyclic Redundancy Check) function

• Supports MS 4-bit parallel transfer mode

• Supports MS-PRO 4-bit parallel transfer mode

• Supports MS PRO-HG Duo 4-bit parallel transfer mode

Supports SD 4-bit parallel transfer mode

• Supports high-speed 50Mhz SD 4-bit card (version 2.0)

Supports high-speed 52Mhz MMC 8-bit card (version 4.2)

• Supports CF v4.0 with PIO mode 6 and Ultra DMA mode

Supported media type

CompactFlash Type I

CompactFlash Type II

Microdrive

MultiMediaCard (MMC)

• Reduced Size MultiMediaCard (RS MMC)

MultiMediaCard 4.2 (MMC Plus, including MMC Plus HC)

 Reduced Size MultiMediaCard 4.2 (MMC Mobile, including MMC Mobile HC)

Secure Digital Card (SD)

Secure Digital High Capacity (SDHC)

miniSD

miniSD High Capacity

Micro SD (T-Flash)

Micro SD HC

Memory Stick

Memory Stick Select

Memory Stick Duo (MS Duo)

Memory Stick PRO (MS PRO)

Memory Stick PRO Duo (MS PRO Duo)

Memory Stick PRO-HG Duo

MagicGate Memory Stick (MG)

MagicGate Memory Stick Duo

xD-Picture Card

Supported media type with card adapter

Environmental

Memory Stick Micro (M2)

MMC Micro

Operational
Environmental Extremes

Test Parameters/Conditions - Power applied, unit

operating on system $\pm 5\%$ nominal supply voltage. 10°C 10% R.H. = 24 hours

10°C 90% R.H. = 24 hours 20°C 90% R.H. = 24 hours 30°C 90% R.H. = 24 hours

 40° C 90% R.H. = 24 hours 50° C 90% R.H. = 24 hours

Technical Specifications - Removable Storage

50°C 10% R.H. = 24 hours

Storage Environmental

Extremes

Test Parameters/Conditions

140°F (60°C) @ 80% R.H. for 96 hours -22°F (-30°C) @ 20% R.H. for 48 hours

No power applied Delta °C < 1.0°C/min

Delta % R.H. < 1.5% R.H./min

Approvals

USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0, Compliant Intel Front Panel I/O Connectivity Design

Guide V. 1.3

FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUV-T



Technical Specifications - Environmental Data

Microtower

Eco-Label Certifications and declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- US Energy Star
- IT ECO declaration
- EPEAT Gold

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Microtower model is based on a typically configured product.

	,	1 / 5 1	
Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	31.3720 W	32.1179 W	31.8169 W
Sleep (Energy Star low power mode)	2.4746 W	2.6361 W	2.4347 W
Off	0.7153 W	0.8560 W	0.6980 W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	107 BTU/hr	110 BTU/hr	109 BTU/hr
Sleep	8 BTU/hr	9 BTU/hr	8 BTU/hr
Off	2 BTU/hr	3 BTU/hr	2 BTU/hr

^{*} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions

(in accordance with ISO 7779 and ISO 9296)

	Sound Power	Sound Pressure
System Fan Off	(LWAd, bels)	(LpAm, decibels)
Idle	3.8	27
Fixed Disk (random writes)	3.8	28

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Li Ion

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and



Technical Specifications - Environmental Data

ISO1043.

• This product contains 0% post consumer recycled plastic (by wt.)

• This product is 91.4% recyclable when properly disposed of at end of life.

Packaging Materials External

Corrugated Paper 1835 g

Internal

Polyethylene low density solid 150 g Polyethylene low density foam 20 g

• The Polyethylene low density foam packaging material is made from 100% recycled content.

- The Polyethylene low density Solid packaging material is made from 100% recycled content.
- The corrugated packaging material contains at least 30% recycled content.

Small Form Factor

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be declarations labeled with one or more of these marks:

- US Energy Star
- IT ECO declaration
- EPEAT Gold

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Small Form Factor model is based on a typically configured product.

28

Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	27.4159 W	27.1680 W	27.7080 W
Sleep (Energy Star low power mode)	2.5527 W	2.7644 W	2.5316 W
Off	0.7149 W	0.8667 W	0.7003 W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	94 BTU/hr	93 BTU/hr	95 BTU/hr
Sleep	9 BTU/hr	9 BTU/hr	9 BTU/hr
Off	2 BTU/hr	3 BTU/hr	2 BTU/hr

^{*} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions

(in accordance with ISO 7779 and ISO 9296)

Fixed Disk (random

Sound Power
System Fan Off (LWAd, bels) (LpAm, decibels)
Idle 3.8 27

3.9

writes)





Technical Specifications - Environmental Data

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Li Ion

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 0% post consumer recycled plastic (by wt.)
- This product is 95.1% recyclable when properly disposed of at end of life.

Packaging Materials External

Corrugated Carton 1705 g

Internal

EPE-Expanded Polyethylene 198 g Polyethylene low density foam 39 g

- The EPE-Expanded Polyethylene packaging material is made from 100% recycled content.
- The Polyethylene low density foam packaging material is made from 100% recycled content.
- The Corrugated Carton packaging materials contains at least 75% recycled content.

Small Form Factor and Microtower

RoHS Compliance

Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the

Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes



Technical Specifications - Environmental Data

- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Hewlett-Packard Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html



Technical Specifications - Environmental Data

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